

#### **ABSTRACT OF THE DISCLOSURE**

The method of the present invention is a method for forming a solder-resist film on a circuit board having patterned circuit conductor parts at least on one face and involves steps  
5 of forming a resin layer between neighboring circuit conductor parts by applying a liquid-phase curable resin so as to fill grooves between the neighboring circuit conductor parts and forming a solder-resist film by applying a solder resist to the circuit board having the resin layer.